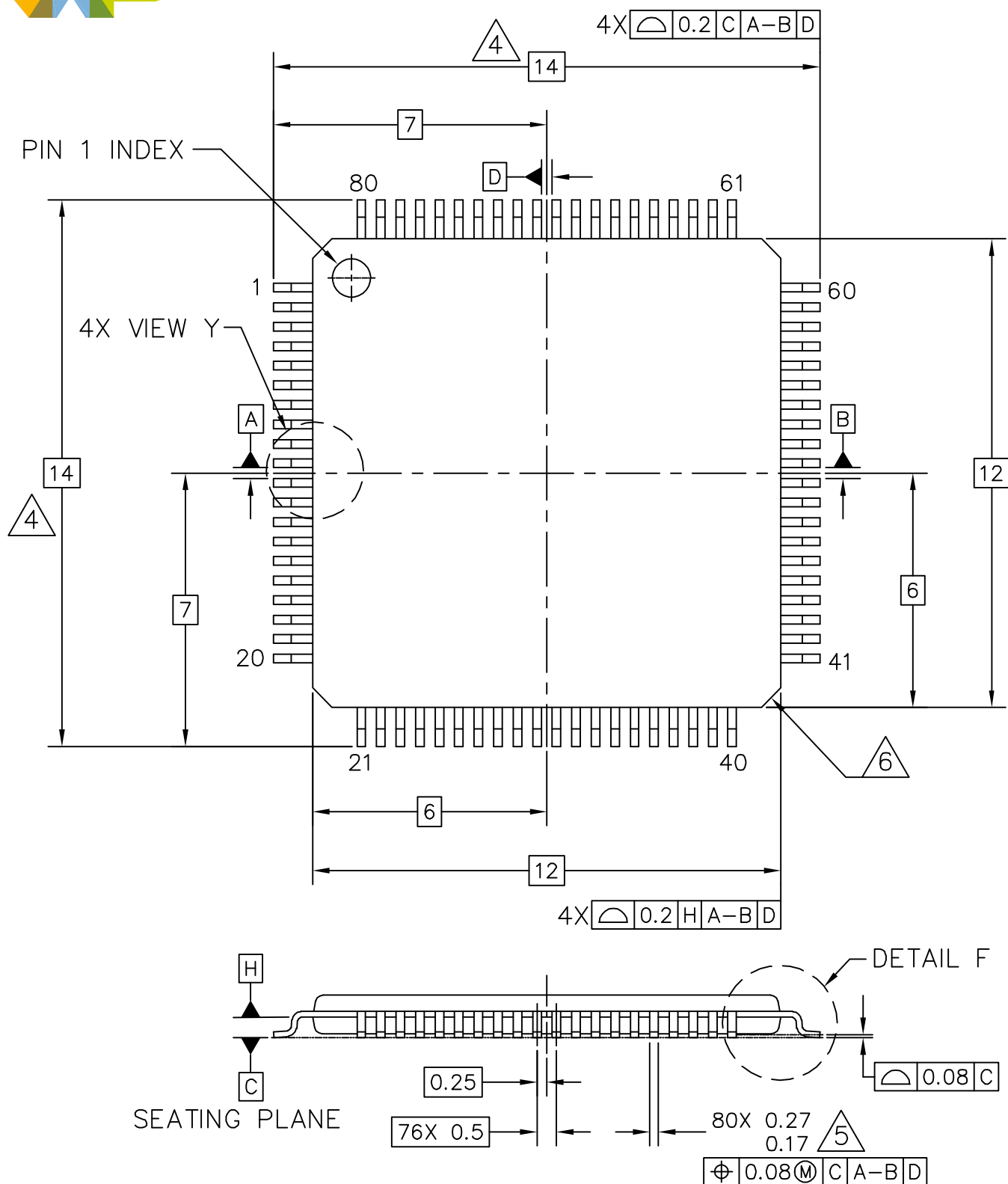
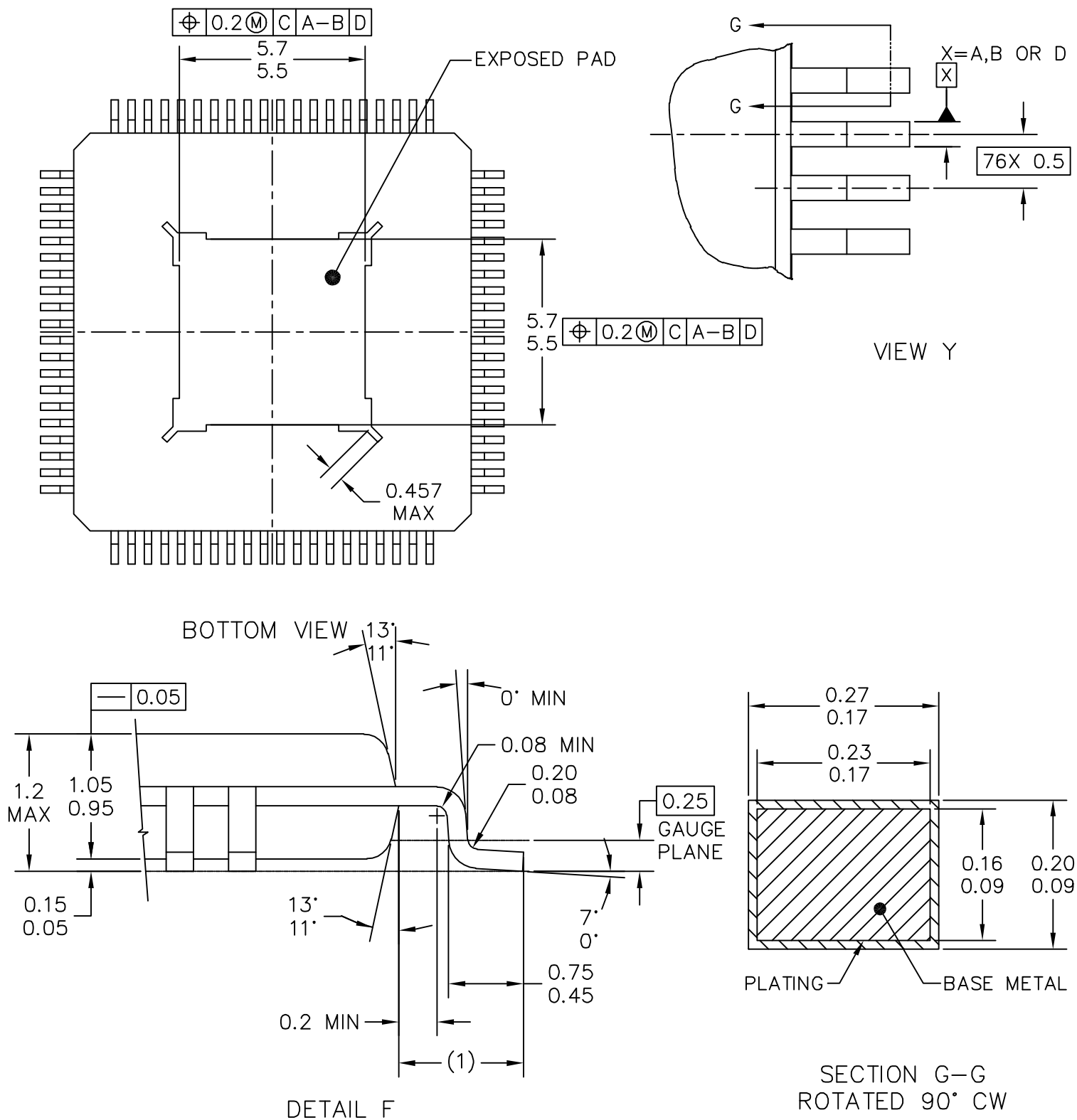




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TITLE: TQFP, 80 I/O, EXPOSED PAD, 12X12X1 PKG, 0.5 PITCH	DOCUMENT NO: 98ASA10811D	REV: A
	STANDARD: JEDEC MS-026 ADD	
	SOT841-5	18 JAN 2016



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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED WHERE THE LEADS EXIT THE PLASTIC BODY AT DATUM PLANE H.
4. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08MM. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN A PROTRUSION AND AN ADJACENT LEAD IS 0.07MM.
6. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

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